DATA SHEET

74F382
Arithmetic Logic Unit

Product specification

1990 Jul 12

IC15 Data Handbook

Philips
Semiconductors

PHILIPS

Arithmetic logic unit 74F382

FEATURES

- Performs six arithmetic and logic functions
- Selectable Low (clear) and High (preset) functions
- Low-input loading minimizes drive requirements
- Carry output for ripple expansion
- Overflow output for Two's Complement arithmetic

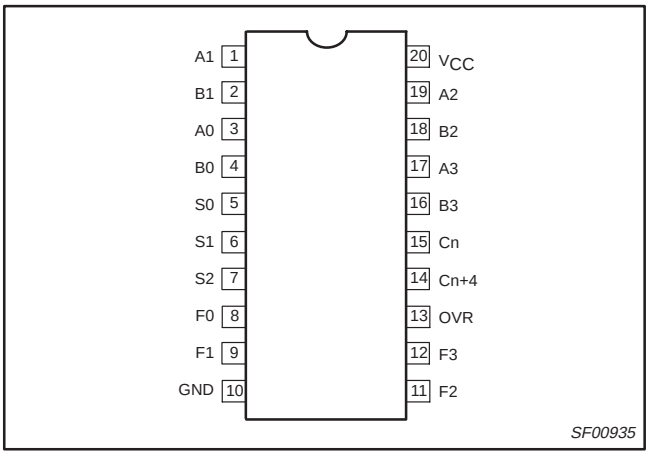
DESCRIPTION

The 74F382 performs three arithmetic and three logic operations on two 4-bit words, A and B. Two additional Select (S0–S2) input codes force the Function outputs Low or High. An overflow output is provided for convenience in Two's Complement arithmetic.

A carry output is provided for ripple expansion. For high-speed expansion using a carry look-ahead generator, refer to the 74F381 data sheet.

Signals applied to the Select inputs, S0–S2, determine the mode of operation, as indicated in the Function Select Table. An extensive listing of input and output levels is shown in the Function Table. The circuit performs the arithmetic functions for either active-HIgh or active-Low operands, with output levels in the same convention. In the subtract operating modes, it is necessary to force a carry (High for active-HIgh operands, Low for active-Low operands) into the Cn input of the least significant package. Ripple expansion is illustrated in Figure 1. The overflow output OVR is the Exclusive-OR of Cn+3 and Cn+4; a High signal on OVR indicates overflow in Two's complement operation (See Table 2 for Two's complement arithmetic). Typical delays for Figure 1 are given in Table 1. When the 74F382 is cascaded to handle word lengths longer than 4 bits, only the most significant overflow (OVR) output is used.

PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F382	7.0ns	54mA

ORDERING INFORMATION

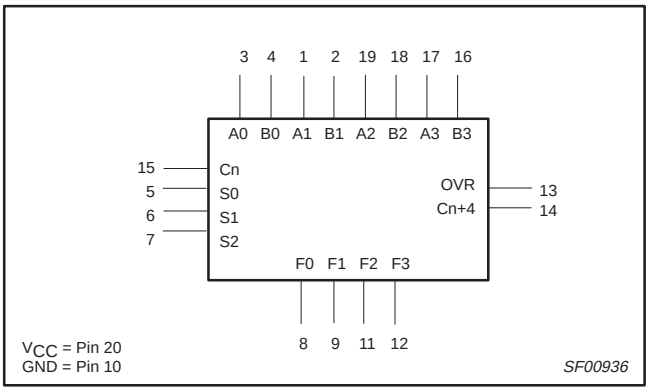
DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T_{amb} = 0°C to +70°C	PKG DWG #
20-pin plastic DIP	N74F382N	SOT146-1
20-pin plastic SO	N74F382D	SOT163-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

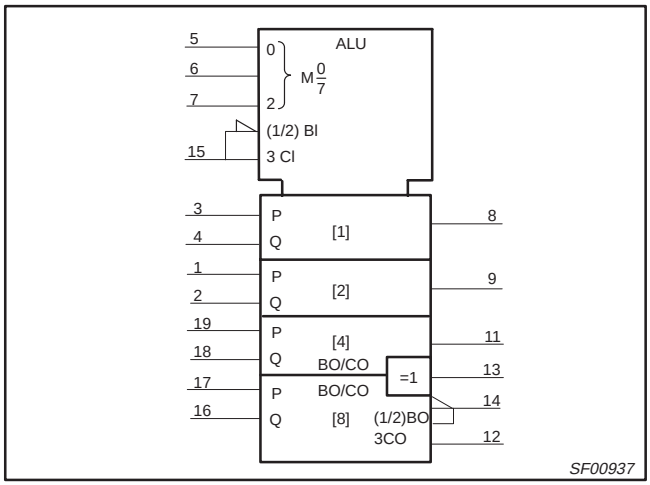
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0 – A3	A operand inputs	1.0/4.0	20µA/2.4mA
B0 – B3	B operand inputs	1.0/4.0	20µA/2.4mA
S0 – S2	Function select inputs	1.0/1.0	20µA/0.6mA
Cn	Carry input	1.0/5.0	20µA/3.0mA
Cn+4	Carry output	50/33	1.0mA/20mA
OVR	Overflow output	50/33	1.0mA/20mA
F0–F3	Outputs	50/33	1.0mA/20mA

NOTE:
One (1.0) FAST unit load is defined as 20µA in the High state and 0.6mA in the Low state.

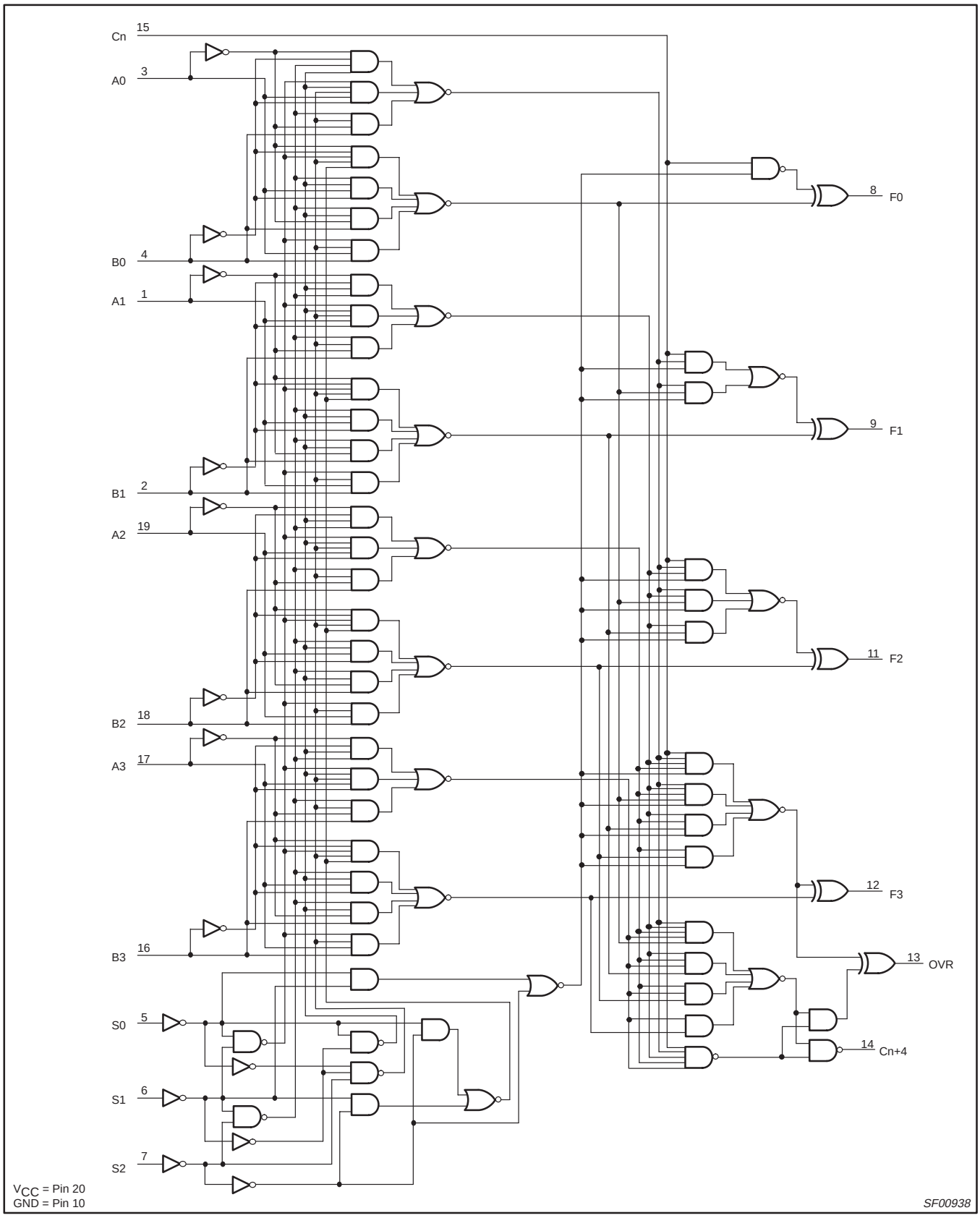
LOGIC SYMBOL



IEC/IEEE SYMBOL



LOGIC DIAGRAM



FUNCTION TABLE

INPUTS						OUTPUTS						OPERANDS	OPERATING MODE
S0	S1	S2	Cn	An	Bn	F0	F1	F2	F3	OVR	Cn+4		
L	L	L	L	X	X	L	L	L	L	H	H		Clear
L	L	L	H	X	X	L	L	L	L	H	H		
H	L	L	L	L	L	H	H	H	H	L	L	Active-Low	B minus A
H	L	L	L	L	H	L	H	H	H	L	H		
H	L	L	L	H	L	L	L	L	L	L	L		
H	L	L	L	H	H	H	H	H	H	L	L		
H	L	L	H	L	L	L	L	L	L	L	H	Active-High	
H	L	L	H	L	H	H	H	H	H	L	H		
H	L	L	H	H	L	H	L	L	L	L	L		
H	L	L	H	H	H	L	L	L	L	L	H		
L	H	L	L	L	L	H	H	H	H	L	L	Active-Low	A minus B
L	H	L	L	L	H	L	L	L	L	L	L		
L	H	L	L	H	L	L	H	H	H	L	H		
L	H	L	L	H	H	H	H	H	H	L	L		
L	H	L	H	L	L	L	L	L	L	L	H	Active-High	
L	H	L	H	L	H	H	L	L	L	L	L		
L	H	L	H	H	L	H	H	H	H	L	H		
L	H	L	H	H	H	L	L	L	L	L	H		
H	H	L	L	L	L	L	L	L	L	L	L		A Plus B
H	H	L	L	L	H	H	H	H	H	L	L		
H	H	L	L	H	L	H	H	H	H	L	L		
H	H	L	L	H	H	L	H	H	H	L	H		
H	H	L	H	L	L	H	L	L	L	L	L		
H	H	L	H	L	H	L	L	L	L	L	H		
H	H	L	H	H	L	L	L	L	L	L	H		
H	H	L	H	H	H	H	H	H	H	L	H		
L	L	H	X	L	L	L	L	L	L	L	L		A ⊕ B
L	L	H	X	L	H	H	H	H	H	L	L		
L	L	H	L	H	L	H	H	H	H	L	L		
L	L	H	X	H	H	L	L	L	L	H	H		
L	L	H	H	H	L	H	H	H	H	H	H		
H	L	H	X	L	L	L	L	L	L	L	L		A + B
H	L	H	X	L	H	H	H	H	H	L	L		
H	L	H	X	H	L	H	H	H	H	L	L		
H	L	H	L	H	H	H	H	H	H	L	L		
H	L	H	H	H	H	H	H	H	H	H	H		
L	H	H	X	L	L	L	L	L	L	H	H		AB
L	H	H	X	L	H	L	L	L	L	L	L		
L	H	H	X	H	L	L	L	L	L	H	H		
L	H	H	L	H	H	H	H	H	H	L	L		
L	H	H	H	H	H	H	H	H	H	H	H		
H	H	H	X	L	L	H	H	H	H	L	L		Preset
H	H	H	X	L	H	H	H	H	H	L	L		
H	H	H	X	H	L	H	H	H	H	L	L		
H	H	H	L	H	H	H	H	H	H	L	L		
H	H	H	H	H	H	H	H	H	H	H	H		

H = High voltage level
L = Low voltage level
X = Don't care

FUNCTION SELECT TABLE

SELECT			OPERATING MODE
S0	S1	S2	
L	L	L	Clear
H	L	L	B minus A
L	H	L	A minus B
H	H	L	A Plus B
L	L	H	A ⊕ B
H	L	H	A + B
L	H	H	AB
H	H	H	Preset

H = High voltage level
L = Low voltage level

Table 1. 16-Bit Delay Tabulation

PATH SEGMENT	TOWARD F	OUTPUT Cn+4, OVR
Ai or Bi to Cn+4	6.5ns	6.5ns
Cn to Cn+4	6.3ns	6.3ns
Cn to Cn+4	6.3ns	6.3ns
Cn to F	8.1ns	–
Cn to Cn+4, OVR	–	8.0ns
Total Delay	27.2ns	27.1ns

Table 2. Two's Complement Arithmetic

MSB			LSB	Numerical Values
L	L	L	L	0
L	L	L	H	1
L	L	H	L	2
L	L	H	H	3
L	H	L	L	4
L	H	L	H	5
L	H	H	L	6
L	H	H	H	7
H	L	L	L	–8
H	L	L	H	–7
H	L	H	L	–6
H	L	H	H	–5
H	H	L	L	–4
H	H	L	H	–3
H	H	H	L	–2
H	H	H	H	–1

H = High voltage level
L = Low voltage level

APPLICATION

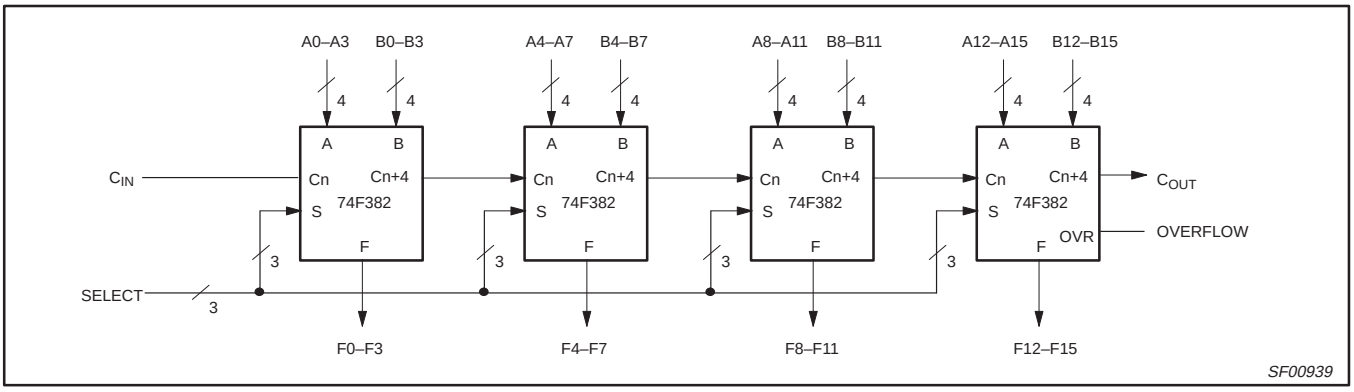


Figure 1. 16-bit Look-ahead Carry ALU Expansion

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	–0.5 to +7.0	V
V_{IN}	Input voltage	–0.5 to +7.0	V
I_{IN}	Input current	–30 to +1	mA
V_{OUT}	Voltage applied to output in High output state	–0.5 to +V_{CC}	V
I_{OUT}	Current applied to output in Low output state	40	mA
T_{amb}	Operating free-air temperature range	0 to +70	°C
T_{stg}	Storage temperature range	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARMETER SYMBOL	LIMITS			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			–18	mA
I_{OH}	High-level output current			–1	mA
I_{OL}	Low-level output current			20	mA
T_{amb}	Operating free-air temperature range	0		70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIONS[1]		LIMITS			UNIT
					MIN	TYP[2]	MAX	
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IL} = MAX,	±10%V_{CC}	2.5			V
			V_{IH} = MIN, I_{OH} = MAX	±5%V_{CC}	2.7	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IL} = MAX,	±10%V_{CC}		0.30	0.50	V
			V_{IH} = MIN, I_{OL} = MAX	±5%V_{CC}		0.30	0.50	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = I_{IK}			–0.73	–1.2	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 7.0V				100	µA
I_{IH}	High-level input current		V_{CC} = MAX, V_I = 2.7V				20	µA
I_{IL}	Low-level input current	Cn	V_{CC} = MAX, V_I = 0.5V				–3.0	mA
		A0–A3, B0–B3					–2.4	mA
		S0, S1, S2					–0.6	mA
I_{OS}	Short-circuit output current[3]		V_{CC} = MAX		–60		–150	mA
I_{CC}	Supply current (total)		V_{CC} = MAX			54	81	mA

NOTES:

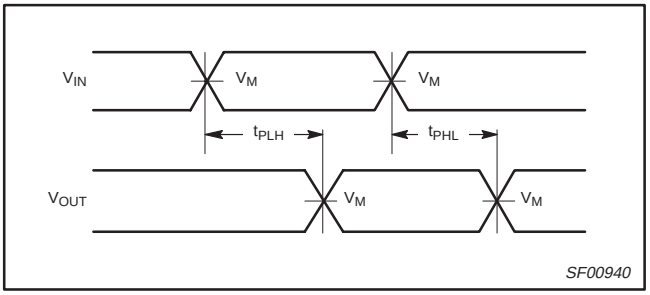
1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			T_{amb} = +25°C V_{CC} = +5.0V C_L = 50pF, R_L = 500Ω			T_{amb} = 0°C to +70°C V_{CC} = +5.0V ± 10% C_L = 50pF, R_L = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t_{PLH} t_{PHL}	Propagation delay Cn to Fn	Waveform 1	3.0 2.5	7.0 4.5	12.0 6.5	2.5 2.5	13.5 7.5	ns
t_{PLH} t_{PHL}	Propagation delay An or Bn to Fn	Waveform 1	3.5 3.0	8.0 6.0	13.5 10.0	3.5 2.5	17.0 11.0	ns
t_{PLH} t_{PHL}	Propagation delay Si to Fi	Waveform 1	5.5 5.5	9.0 7.5	15.0 10.5	5.5 5.5	16.0 12.0	ns
t_{PLH} t_{PHL}	Propagation delay Ai to Bi to Cn+4	Waveform 1	3.5 3.5	7.0 6.5	10.5 9.5	3.5 3.5	11.5 10.5	ns
t_{PLH} t_{PHL}	Propagation delay Si to OVR or Cn+4	Waveform 1	7.0 5.0	10.5 8.0	14.5 11.0	6.5 5.0	17.0 12.0	ns
t_{PLH} t_{PHL}	Propagation delay Cn to Cn+4	Waveform 1	3.0 3.5	4.5 5.0	6.0 6.5	2.5 3.5	6.5 7.0	ns
t_{PLH} t_{PHL}	Propagation delay Cn to OVR	Waveform 1	4.5 3.0	9.0 5.0	13.5 6.5	4.0 3.0	15.0 7.0	ns
t_{PLH} t_{PHL}	Propagation delay Ai or Bi to OVR	Waveform 1	6.0 3.5	9.0 6.5	12.5 9.0	5.5 3.5	16.5 10.0	ns

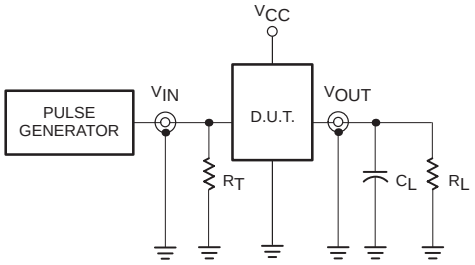
AC WAVEFORMS

For all waveforms, V_M = 1.5V.

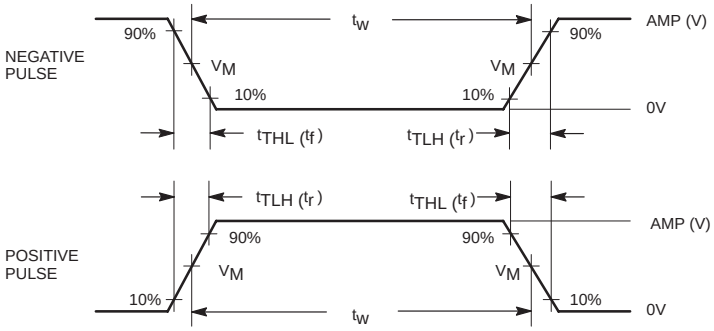


Waveform 1. Propagation Delay for Non-Inverting or Inverting paths

TEST CIRCUIT AND WAVEFORM



Test Circuit for Totem-Pole Outputs



DEFINITIONS:

R_L = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.

C_L = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

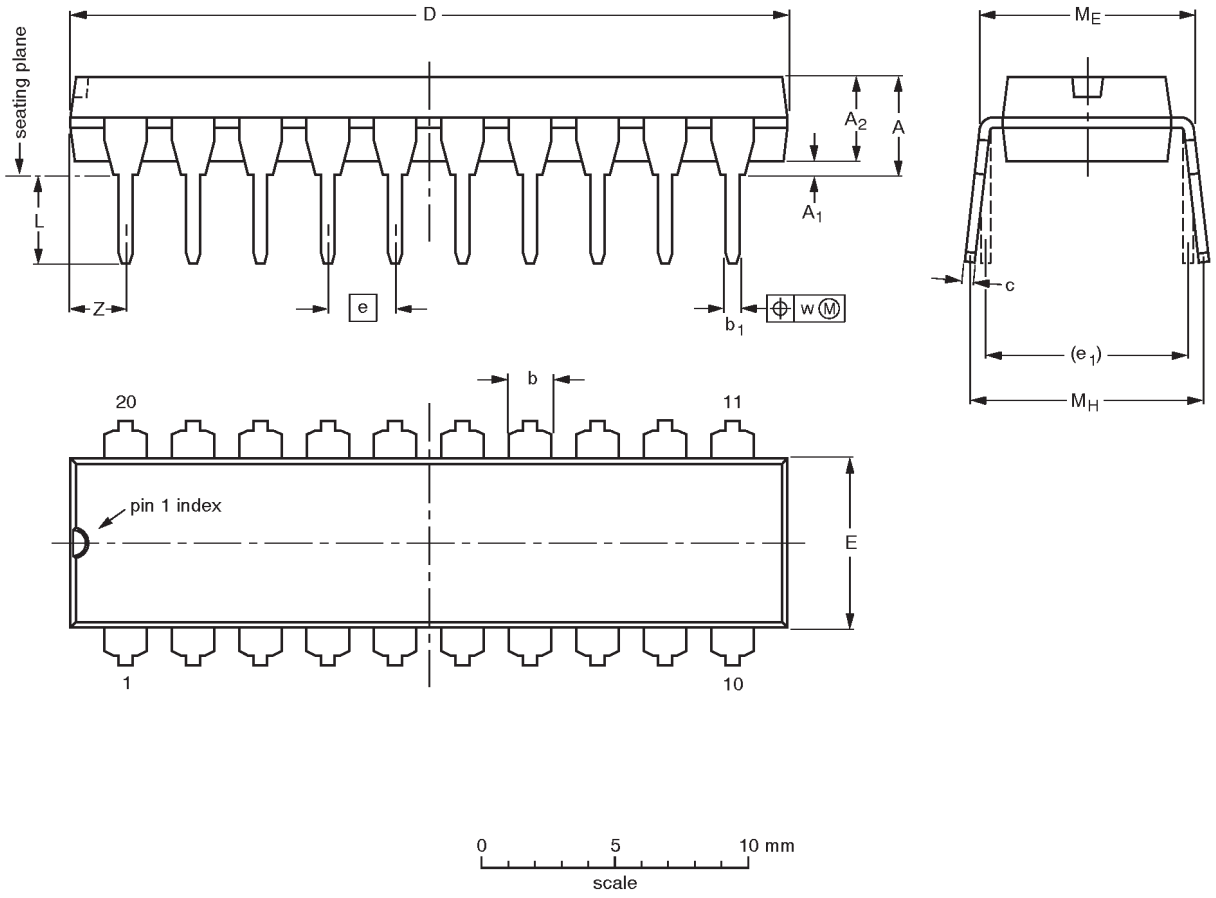
R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

Input Pulse Definition

family	INPUT PULSE REQUIREMENTS					
	amplitude	V_M	rep. rate	t_w	t_{TLH}	t_{THL}
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

SF00006

DIP20: plastic dual in-line package; 20 leads (300 mil) **SOT146-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

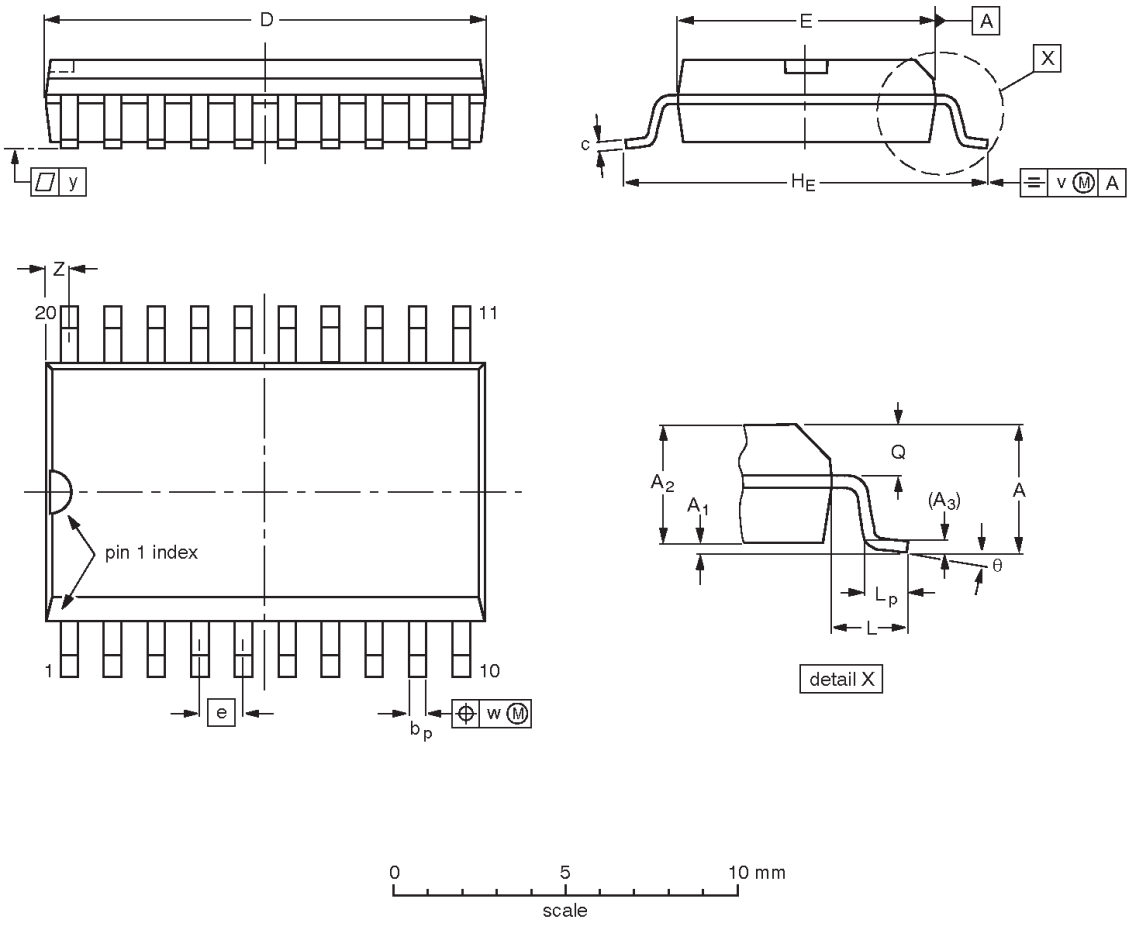
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			~~92-11-17~~ 95-05-24

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				~~95-01-24~~ 97-05-22

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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print code Date of release: 10-98

Document order number: 9397-750-05124

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